LUE Package
32-Lead Plastic Exposed Pad TQFP (5mm × 5mm)
(Reference LTC DWG # 05-08-1986 Rev A)

NOTE:
1. DRAWING CONFORMS TO JEDEC #MS-026 PACKAGE OUTLINE
2. DIMENSIONS ARE IN MILLIMETERS
3. DIMENSIONS OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.25mm ON ANY SIDE, IF PRESENT
4. PIN-1 IDENTIFIER IS A MOLDED INDENTATION
5. EXACT SHAPE OF EACH CORNER IS OPTIONAL
6. DRAWING IS NOT TO SCALE

SECTION A – A

RECOMMENDED SOLDER PAD LAYOUT
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED

GAUGE PLANE

DETAIL "B" CORNER TAIL IS PART OF THE LEADFRAME FEATURE. FOR REFERENCE ONLY. NO MEASUREMENT PURPOSE.